



Please find below our technical specifications.

1. Minimum clearance between

- a) Hole to pad = 0.35 mm
- b) Pad to pad = 0.125 mm
- c) Pad to trace = 0.125 mm
- d) Trace to trace = .125 mm
- e) Hole to hole = 0.30 mm
- f) PCB edge to copper = 0.25 mm
- e) Trace to copper = 0.125 mm

2. Min via size. = 0.30 mm drill & 0.60 mm pad

3. Min BGA pitch. = >1.0 mm

4. Minimum mask clearance = 0.10 mm

5. Minimum annular ring requirement = 0.125 mm (With production hole diameter, PHD = finished hole size + 0.15 mm for PTH holes)

6. Minimum trace thickness = 0.125 mm

7. Drill tolerance = +/- 0.075 mm or -0.05 mm / + 0.10 mm.

8. Minimum board thickness = 0.40 mm

9. Minimum legend width and height = Legend width = 0.15 mm &
Height = 1.5 mm